



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

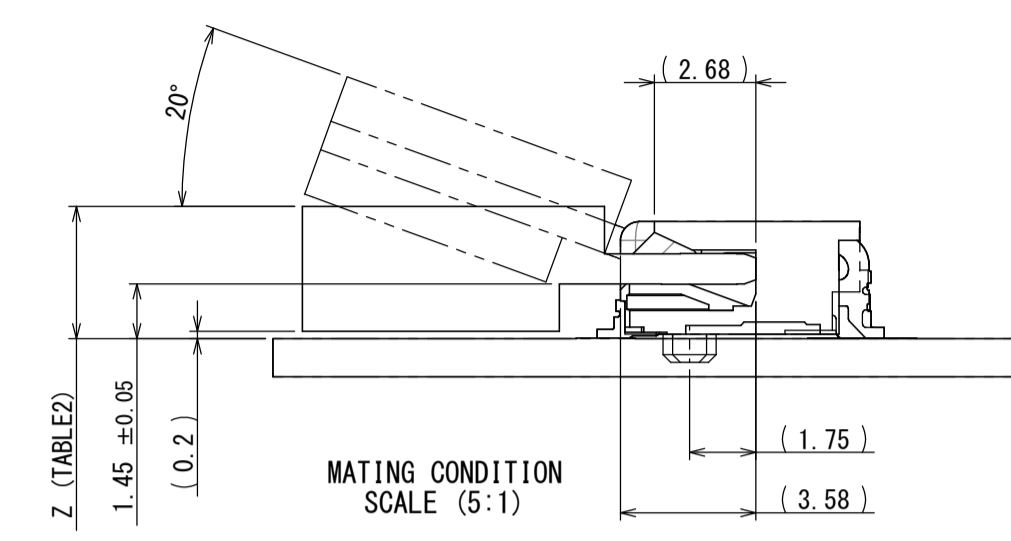
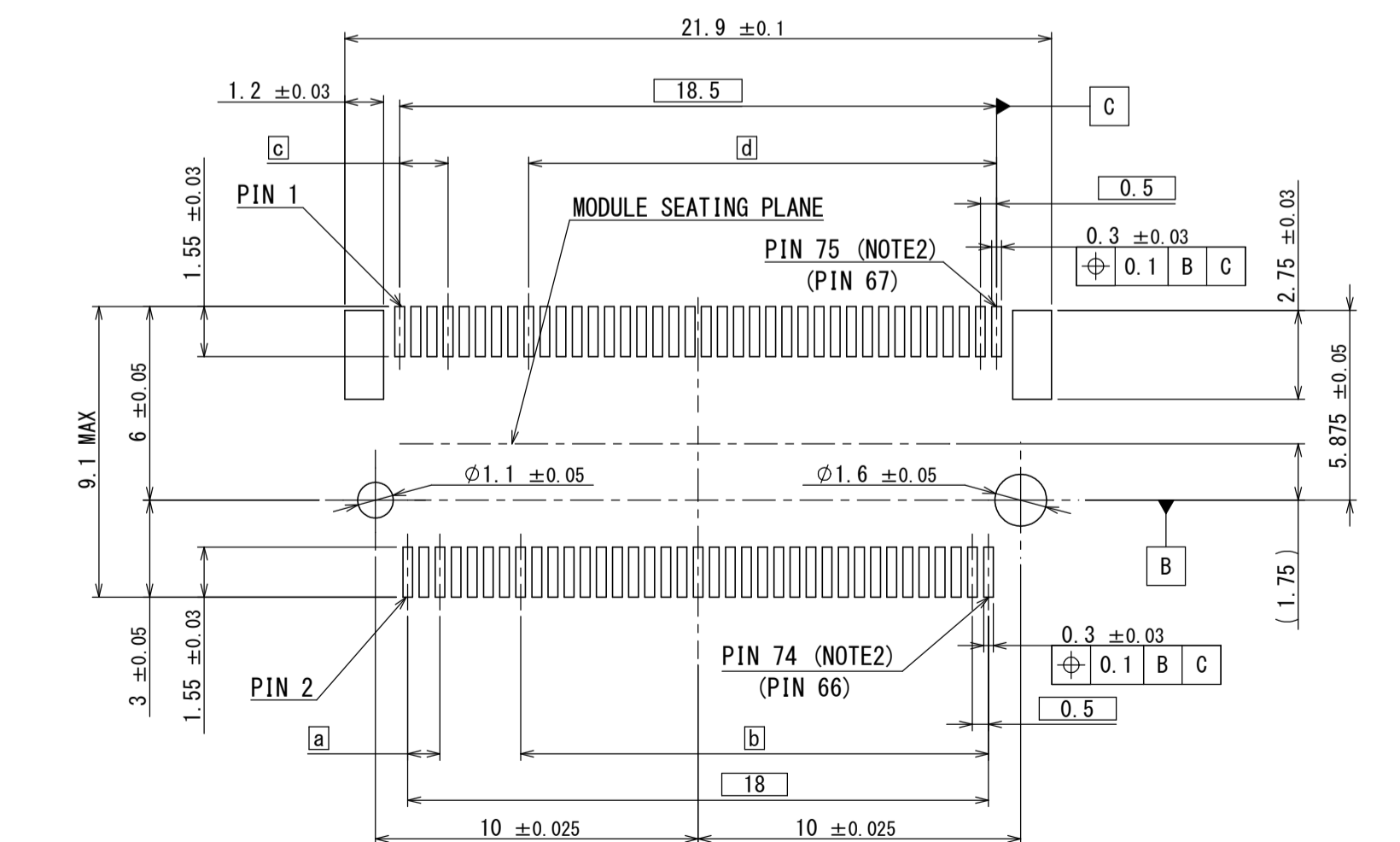
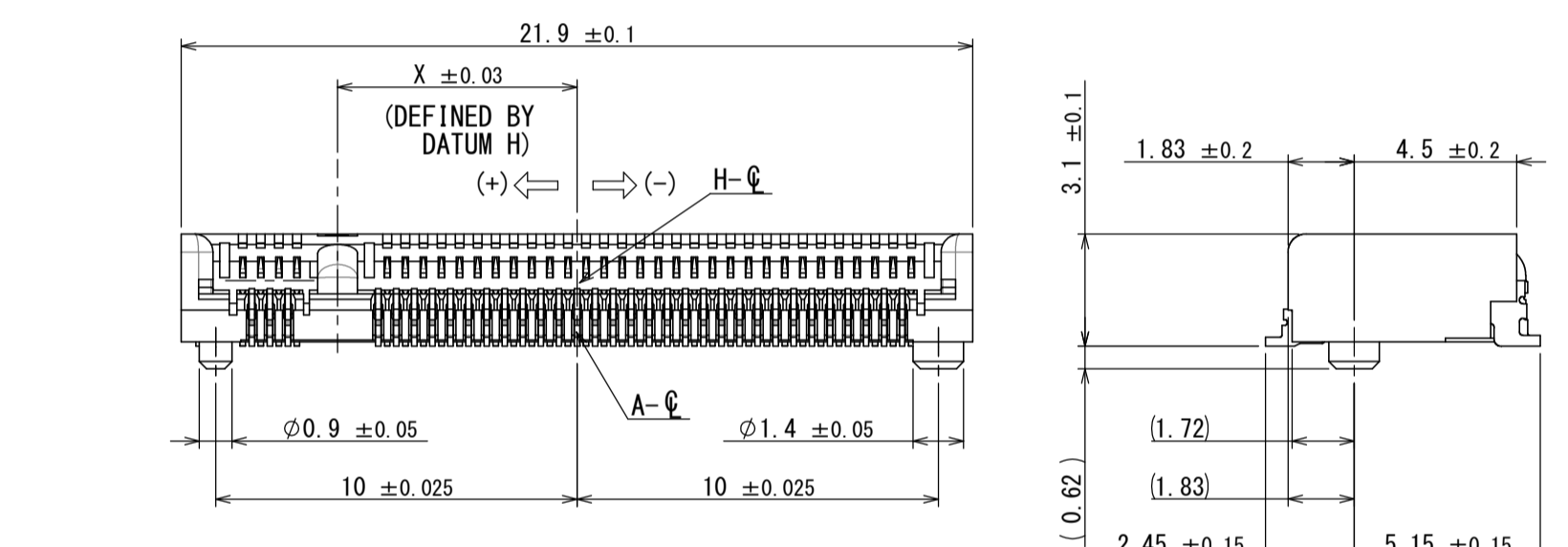
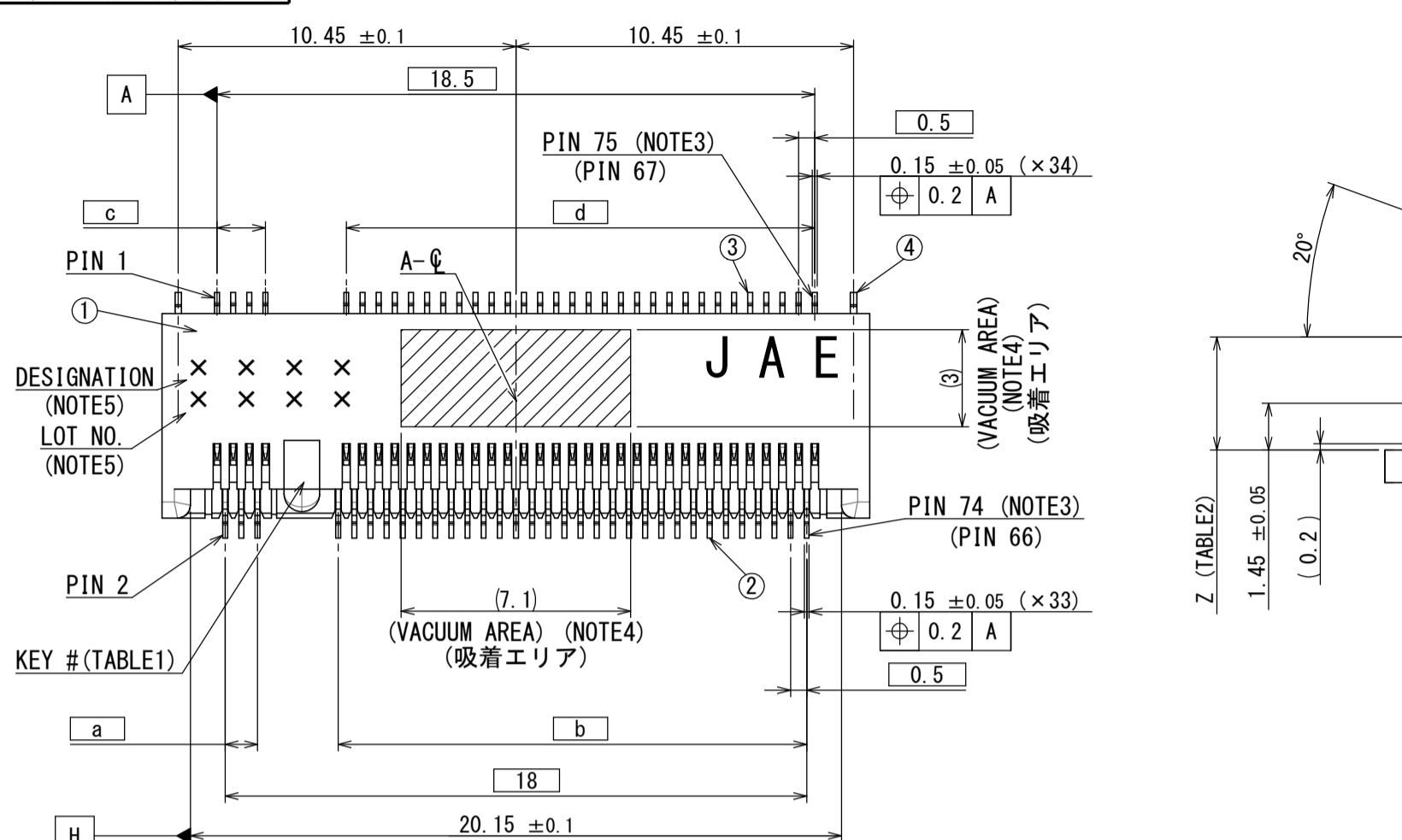
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NOTE5. PRODUCTION LOT No. & MODIFY CODE AS INDICATED.  
(Ex. LOT NO.) I 5 Y B

LOT NUMBER OF CURRENT DAY (SEE TABLE 4)  
MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY, OCT. :0, NOV. :X, DEC. :Y)  
YEAR (LAST DIGIT ONLY)  
MANUFACTURE CODE

(DESIGNATION) S M 3 A

KEY POSITION TYPE: A, B, E, M  
SERIES PREFIX

**DESIGNATION**

SERIES シリーズ SM3ZS067U310※※

KEY POSITION TYPE: A, B, E, M

Z: LIF TYPE  
Z: 低挿入タイプ

S: STANDARD

NO. OF CONTACTS 芯数

MOUNTING TYPE 実装タイプ U: ON BOARD TYPE

CONTACT FINISH 接点仕上げ  
A: Au (0.13 μm MIN)  
B: Au (0.25 μm MIN)

PRODUCT HEIGHT 製品高さ  
215: 2.15mm  
310: 3.10mm  
410: 4.10mm

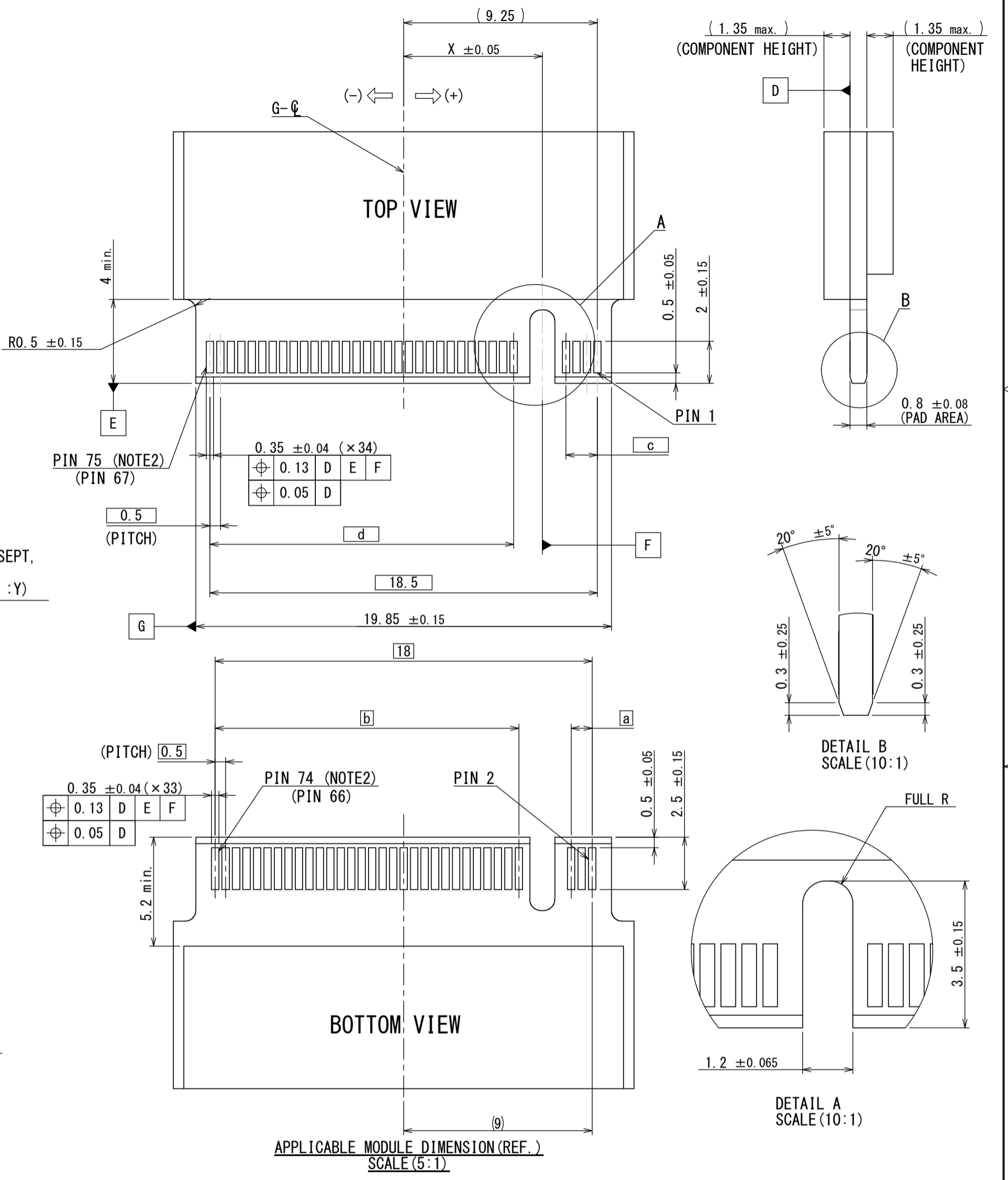
**TABLE 1**

KEY#	X	a	b	c	d
A	+6.625	1	14.5	1.5	14.5
B	+5.625	2	13.5	2.5	13.5
E	+2.625	5	10.5	5.5	10.5
M	-6.125	14	1.5	14	2

**TABLE 2**

COMPONENT HEIGHTS FOR MODULES	Z
1.2 MAX	3.55 MAX RSS
1.35 MAX	3.70 MAX RSS
1.5 MAX	3.85 MAX RSS

NOTE1. THE COPLANARITY OF CONTACT AND HOLD DOWN SHALL BE 0.1 MAXIMUM ON THE SURFACE TABLE.  
NOTE2. THIS NUMBER IS PIN-OUT NUMBER DEFINED BY NGFF SPECIFICATION.  
NOTE3. THIS CONNECTOR IS HALOGEN FREE CORRESPONDENCE PRODUCT.  
NOTE4. THIS AREA SHALL NOT SHOW ANY BURRS AND UNEVEN SURFACE BY EJECTOR PIN MARK, TOOL PARTING LINE, AND ANY OTHER FACTORS.



4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING OVER NI
3	TOP SIDE CONTACT	33	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni
2	BOTTOM SIDE CONTACT	34	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni
1	INSULATOR	1	THERMO PLASTIC	

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 08/JAN/2013	尺度 (SCALE) 5:1	シリーズ (SERIES) SM3	日本航空電子工業株式会社
一般公差 (GENERAL TOLERANCE)	製図 DR. 担当 CHK. S. YAMAGUCHI	名称 (TITLE) SM3ZS067U310※※ (NGFF Double-Sided modules)	JAE JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
寸法 (DIMENSION): ±0.8 × ±0.4 ×× ±0.1 ××× ±	角度 (ANGLES): ×° ± ×' ±	製図 DR. 担当 CHK. R. KATOU	図面番号 (DRAWING NO.) SJ113505	版数 (VER.) 1
単位 (UNIT): mm	承認 APPD. T. SHINDOU	質量 (MASS)		